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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Complete if Known

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| Application Number | 10/614,067 (Conf. No. 8117) |
| Filing Date | July 3, 2003 |
| First Named Inventor | Leedy |
| Art Unit | 2822 |
| Examiner Name | Pamela Perkins |
| Attorney Docket Number | ELM-2 Div. 6 |

Sheet 1 of 3

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| Examiner Signature | /Pamela Perkins/ | Date Considered | 05/08/2006 |
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| | | | | Art Unit | 2822 |
| | | | | Examiner Name | Pamela Perkins |
| Sheet | 2 | of | 3 | Attorney Docket Number | ELM-2 Div. 6 |

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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

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